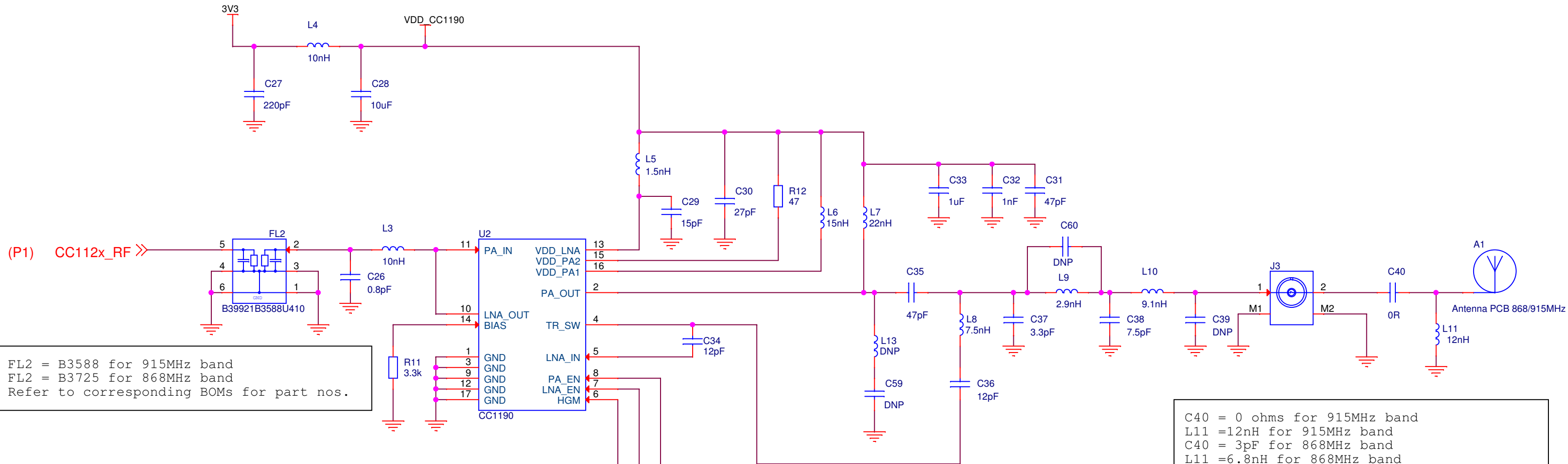


R10 = DNP for Murata IPC  
R10 = 0 ohm for Johanson IPC

Note:  
Case1: For CC112x using XTAL - Do Not Mount C24,C25,R5,R28,CR2 and Mount Y1=32MHz, C22=C23=15pF, R4=0  
Case2: For CC112x using TCXO - Do Not Mount R4,R28,C23,Y1 and Mount C22=0ohm Resistor and U3 = 32MHz  
Case3: For CC120x using XTAL - Do Not Mount C24,C25,R5,R28,CR2 and Mount Y1=40MHz C22=C23=15pF, R4=0  
Case4: For CC120x using TCXO - Do Not Mount R4,R28,C23,Y1 and Mount C22=0 ohm Resistor and U3 = Should be 40MHz  
R5 is the current limiting resistor for TCXO from VDD.R28 is the selection resistor to power-up TCXO from DCPL\_XOSC pin.  
R5 and CR2 can be chosen according to the TCXO power supply requirement.  
If the TCXO is powered-up through R28 then Do not mount R5 and CR2.  
If the TCXO output is square waveform then it should be DC Coupled. Mount C24 = 0 ohm Resistor  
For CC120x - C16 = 1.5nF  
Use R7=0 ohms, R8=R9=DNP for Non-Sigfox Applications

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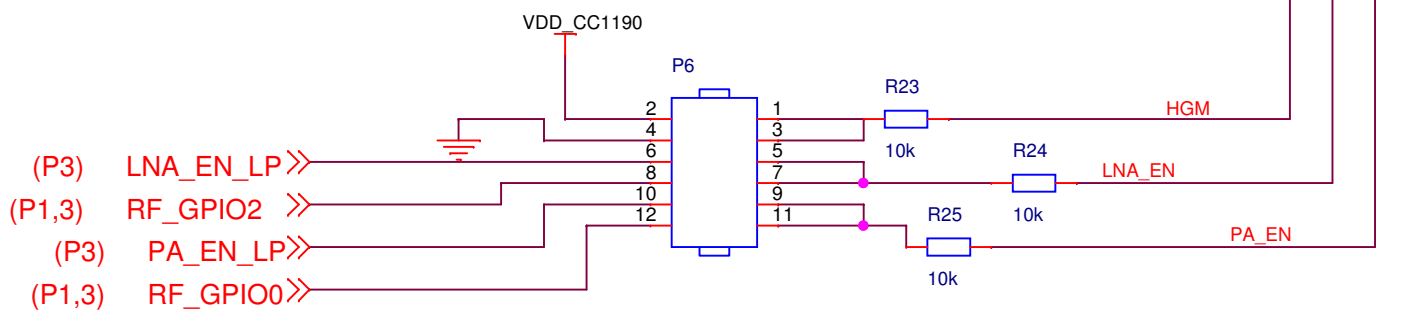


(P1) CC112x\_RF >>

FL2 = B3588 for 915MHz band  
 FL2 = B3725 for 868MHz band  
 Refer to corresponding BOMs for part nos.

C40 = 0 ohms for 915MHz band  
 L11 = 12nH for 915MHz band  
 C40 = 3pF for 868MHz band  
 L11 = 6.8nH for 868MHz band  
 Refer to corresponding BOMs for part nos.

Don not Mount L13, C59 & C60 for 915MHz Design  
 L13, C59 & C60 for 868MHz Design only.  
 Refer to corresponding BOMs for values

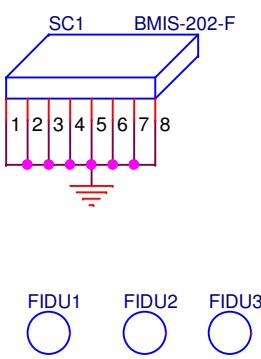


Default Positions (For LaunchPad):  
 Mount Jumper in between 9 & 10  
 Mount Jumper in between 5 & 6  
 Mount Jumper in between 1 & 2

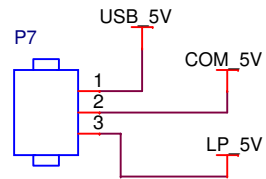
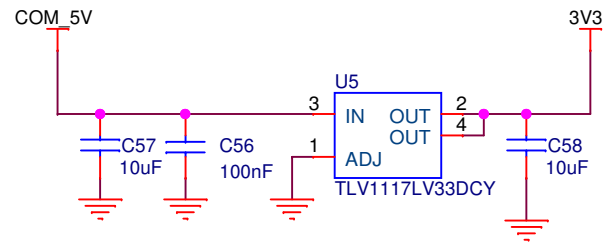
PAEN - Connect 11 & 12 to control from SmartRFStudio  
 LNAEN - Connect 7 & 8 to control from SmartRFStudio  
 Set GPIO2=0x33 & GPIO0 = 0x73 in SRS to set CC1190 in Tx  
 Set GPIO2=0x73 & GPIO0 = 0x33 in SRS to set CC1190 in Rx

PAEN - Connect 9 & 10 to control from LaunchPad  
 LNAEN - Connect 5 & 6 to control from LaunchPad

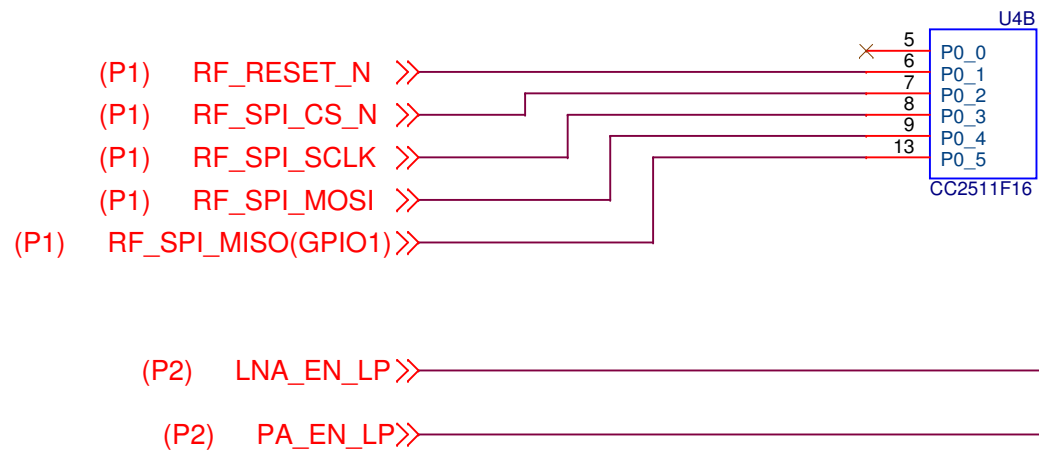
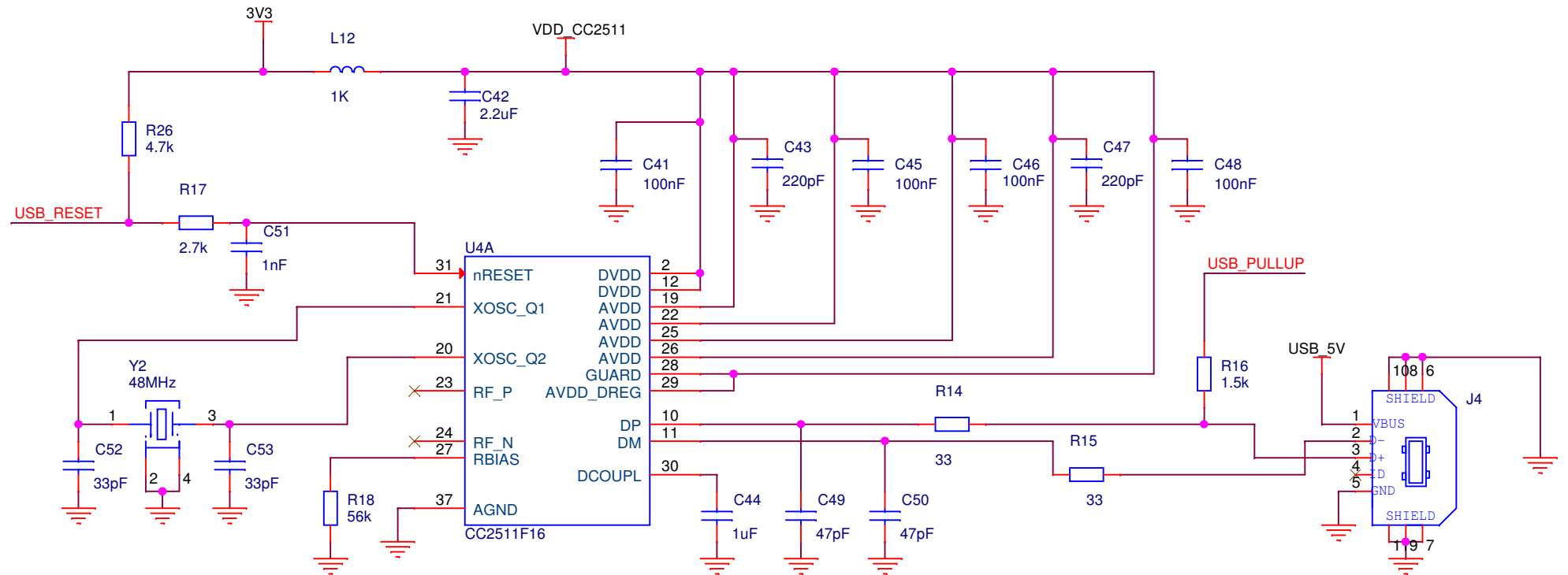
HGM - Connect 1 & 2 to set for High Gain mode  
 HGM - Connect 3 & 4 to set for Low Gain mode



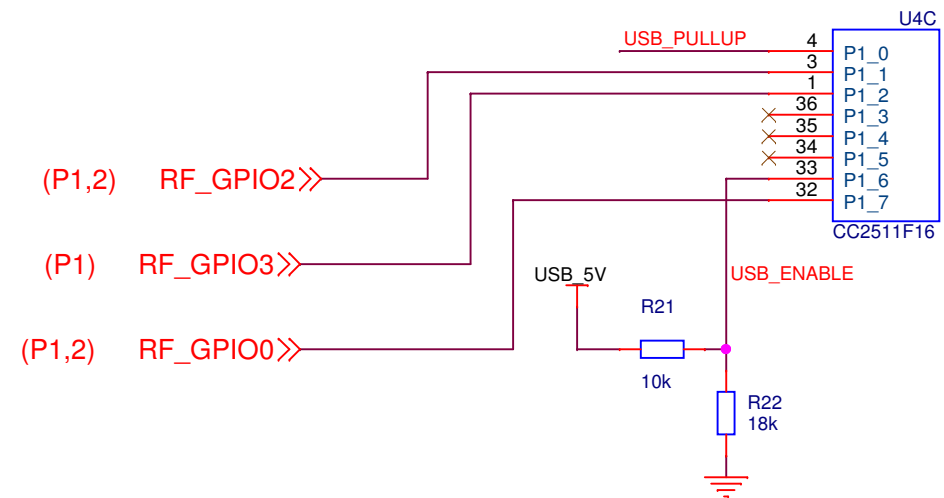
Title: <b>BOOSTXL-CC1120-90</b>		
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Size: B	Rev: A	Sheet: 2 of 3
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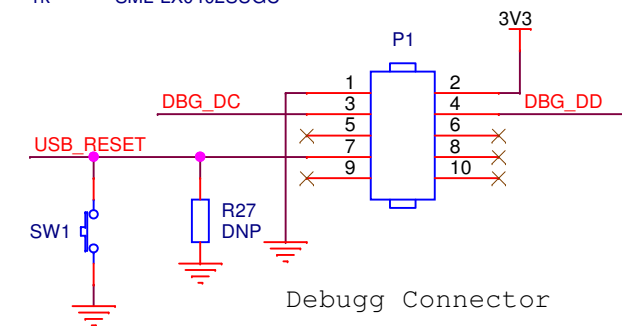
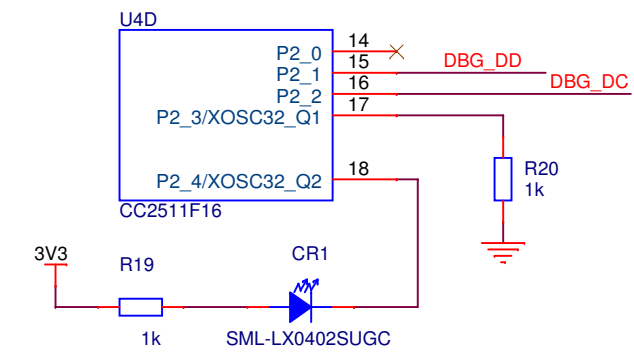
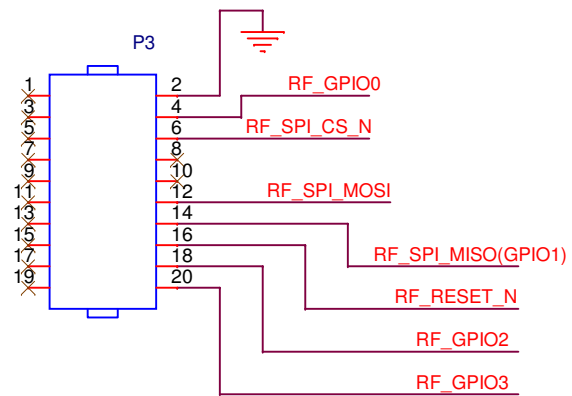
Default Position (For LaunchPad):  
Place Jumper in between 2 & 3  
Connect 1 & 2 - To power-up from the  
ON-Brd USB Connector  
Connect 3 & 2 - To power-up from  
the LaunchPad



LaunchPad Connector (Bottom Mount)  
Place Pin-1 side towards the edge of the PCB



Launch Pad Connector (Bottom Mount)  
Place Pin-2 side towards the edge of the PCB



Title: <b>BOOSTXL-CC1120-90</b>		
Drawn: <b>PM</b>		
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